Wire Pure metal Aluminium (AI) 7429-90-5 0.04524 100 0.75148 Die N/A Silicon Carbide (SiC) 409-21-2 0.01385 100.0 0.23 Die Attach Lead alloy Tin (Sn) 7440-31-5 0.00987 2.0 0.164 Die Attach Lead alloy Silver (Ag) 7440-22-4 0.01234 2.5 0.205 Lead alloy Lead (Pb) 7439-92-1 0.47141 95.5 7.831 Lead Frame Copper alloy Phosphorous (P) 7723-14-0 0.01295 0.03 0.2151 Lead Frame Copper alloy Nickel (Ni) - cas no. 7440-02-0 7440-02-0 0.01295 0.03 0.2151 Lead Frame Copper alloy Iron (Fe) 7439-89-6 0.04316 0.1 0.717 Mould Copper alloy Iron (Fe) 7440-02-0 0.01295 0.03 7158528 Compound Polymer Phenol Formaldehyde resin (generic) 9003-35-4 2.19121 4.0 36.4 Compound <th>External_Type</th> <th>Material_Group</th> <th>Substances</th> <th>CAS_Number</th> <th>Mass</th> <th>Mass_Percentage_in_Leaf</th> <th>Massmg</th>	External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die N/A Silicon Carbide (SiC) 409-21-2 0.01385 100.0 0.23 Subtotal 0.01385 100 0.23 Die Attach Lead alloy Tin (Sn) 7440-31-5 0.00987 2.0 0.164 Lead alloy Silver (Ag) 7440-22-4 0.01234 2.5 0.205 Lead alloy Lead (Pb) 7439-92-1 0.47141 95.5 7.831 Lead Frame Copper alloy Phosphorous (P) 7723-14-0 0.01295 0.03 0.2151 Lead Frame Copper alloy Phosphorous (P) 7440-02-0 0.01295 0.03 0.2151 Copper alloy Inon (Fe) 7440-02-0 0.01295 0.03 0.2151 Mould Copper alloy Copper (Cu) 7440-02-0 0.01295 0.03 717.8528 Mould Polymer Phenol Formaldehyde resin (generic) 9003-35-4 2.19121 4.0 36.4 Mould Epichlorohydrin/Diethyleneglycol generic) 25928-94-3 8.21704 15.0 <td< td=""><td>Wire</td><td>Pure metal</td><td>Aluminium (Al)</td><td>7429-90-5</td><td>0.04524</td><td>100.0</td><td>0.75148</td></td<>	Wire	Pure metal	Aluminium (Al)	7429-90-5	0.04524	100.0	0.75148
Die Attach Lead alloy Tin (Sn) 7440-31-5 0.00987 2.0 0.164 Lead alloy Silver (Ag) 7440-31-5 0.00987 2.0 0.205 Lead alloy Silver (Ag) 7440-22-4 0.01234 2.5 0.205 Lead alloy Lead (Pb) 7439-92-1 0.47141 95.5 7.831 Lead Frame Copper alloy Phosphorous (P) 7723-14-0 0.01295 0.03 0.2151 Lead Frame Copper alloy Nickel (Ni)- cas no. 7440-02-0 7440-02-0 0.01295 0.03 0.2151 Copper alloy ron (Fe) 7439-89-6 0.04316 0.1 0.717 Mould Copper alloy Copper (Cu) 7440-50-8 43.09299 99.84 715.8528 Compound Polymer Phenol Formaldehyde resin (generic) 9003-35-4 2.19121 4.0 36.4 Compound Polymer Epichlorohydrin/Diethyleneglycol 25928-94-3 8.21704 15.0 673.4 Flame retardant Metal hydroxide 58.0				Subtotal	0.04524	100	0.75148
Die Attach Lead alloy Tin (Sn) 7440-31-5 0.00987 2.0 0.164 Lead alloy Silver (Ag) 7440-22-4 0.01234 2.5 0.205 Lead alloy Lead (Pb) 7439-92-1 0.47141 95.5 7.831 Lead Frame Copper alloy Phosphorous (P) 7723-14-0 0.01295 0.03 0.2151 Copper alloy Nickel (Ni) - cas no. 7440-02-0 7440-02-0 0.01295 0.03 0.2151 Copper alloy Iron (Fe) 7439-89-6 0.04316 0.1 0.717 Copper alloy Copper (Cu) 7440-50-8 43.09299 99.84 715.8528 Mould Polymer Phenol Formaldehyde resin (generic) 9003-35-4 2.19121 4.0 36.4 Mould Polymer Epichlorchydrin/Diethyleneglycol Epoxy resin (generic) 25928-94-3 8.21704 15.0 673.4 Flame retardant Metal hydroxide 54,78028 100 910 Post-plating Pure metal Tin (Sn) 7440-31-5 1.50495 <td>Die</td> <td>N/A</td> <td>Silicon Carbide (SiC)</td> <td>409-21-2</td> <td>0.01385</td> <td>100.0</td> <td>0.23</td>	Die	N/A	Silicon Carbide (SiC)	409-21-2	0.01385	100.0	0.23
Lead alloy Silver (Ag) 7440-22-4 0.01234 2.5 0.205 Lead alloy Lead (Pb) 7439-92-1 0.47141 95.5 7.831 Subtotal 0.49362 100 8.2 Lead Frame Copper alloy Phosphorous (P) 7723-14-0 0.01295 0.03 0.2151 Copper alloy Nickel (Ni) - cas no. 7440-02-0 7440-02-0 0.01295 0.03 0.2151 Copper alloy Iron (Fe) 7439-89-6 0.04316 0.1 0.717 Copper alloy Copper (Cu) 7440-50-8 43.09299 9.84 715.8528 Subtotal 43.16205 100 717 Mould Compound Polymer Epichlorohydrin/Diethyleneglycol Epoxy resin (generic) 25928-94-3 8.21704 15.0 136.5 Filler Silica fused 60676-86-0 40.53741 74.0 673.4 Post-plating Pure metal Metal hydroxide Subtotal 54.78028 100 910 Post-plating Pure metal Tin (Sn)				Subtotal	0.01385	100	0.23
Lead alloy Lead (Pb) 7439-92-1 0.47141 95.5 7.831 Lead Frame Copper alloy Phosphorous (P) 7723-14-0 0.01295 0.03 0.2151 Copper alloy Nickel (Ni) - cas no. 7440-02-0 7440-02-0 0.01295 0.03 0.2151 Copper alloy Iron (Fe) 7439-89-6 0.04316 0.1 0.717 Copper alloy Copper (Cu) 7440-50-8 43.09299 99.84 715.8528 Mould Compound Polymer Phenol Formaldehyde resin (generic) 9003-35-4 2.19121 4.0 36.4 Mould Compound Filler Silica fused 60676-86-0 40.53741 74.0 673.4 Filler Silica fused 60676-86-0 40.53741 74.0 673.4 Post-plating Pure metal Tin (Sn) 7440-31-5 1.50495 100.0 25	Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.00987	2.0	0.164
Lead Frame Copper alloy Phosphorous (P) 7723-14-0 0.01295 0.03 0.2151 Copper alloy Nickel (NI) - cas no. 7440-02-0 7440-02-0 0.01295 0.03 0.2151 Copper alloy Iron (Fe) 7439-89-6 0.04316 0.1 0.717 Copper alloy Copper (Cu) 7440-50-8 43.09299 99.84 715.8528 Mould Compound Polymer Phenol Formaldehyde resin (generic) 9003-35-4 2.19121 4.0 36.4 Polymer Epichlorohydrin/Diethyleneglycol Epoxy resin (generic) 25928-94-3 8.21704 15.0 136.5 Filler Silica fused 60676-86-0 40.53741 74.0 673.4 Post-plating Metal hydroxide Subtotal 54.78028 100 910 Post-plating Pure metal Tin (Sn) 7440-31-5 1.50495 100.0 25		Lead alloy	Silver (Ag)	7440-22-4	0.01234	2.5	0.205
Lead Frame Copper alloy Phosphorous (P) 7723-14-0 0.01295 0.03 0.2151 Copper alloy Nickel (Ni) - cas no. 7440-02-0 7440-02-0 0.01295 0.03 0.2151 Copper alloy Iron (Fe) 7439-89-6 0.04316 0.1 0.717 Copper alloy Copper (Cu) 7440-50-8 43.09299 99.84 715.8528 Mould Compound Polymer Phenol Formaldehyde resin (generic) 9003-35-4 2.19121 4.0 36.4 Polymer Epichlorohydrin/Diethyleneglycol Epoxy resin (generic) 25928-94-3 8.21704 15.0 136.5 Filler Silica fused 60676-86-0 40.53741 74.0 673.4 Post-plating Metal hydroxide 54.78028 100 910 Post-plating Pure metal Tin (Sn) 7440-31-5 1.50495 100.0 25		Lead alloy	Lead (Pb)	7439-92-1	0.47141	95.5	7.831
Copper alloy Nickel (Ni) - cas no. 7440-02-0 7440-02-0 0.01295 0.03 0.2151				Subtotal	0.49362	100	8.2
Copper alloy Iron (Fe) 7439-89-6 0.04316 0.1 0.717 Copper alloy Copper (Cu) 7440-50-8 43.09299 99.84 715.8528 Mould Compound Polymer Phenol Formaldehyde resin (generic) 9003-35-4 2.19121 4.0 36.4 Polymer Epichlorohydrin/Diethyleneglycol Epoxy resin (generic) 25928-94-3 8.21704 15.0 136.5 Filler Silica fused 60676-86-0 40.53741 74.0 673.4 Flame retardant Metal hydroxide subtotal 54.78028 100 910 Post-plating Pure metal Tin (Sn) 7440-31-5 1.50495 100.0 25	Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01295	0.03	0.2151
Copper alloy Copper (Cu) 7440-50-8 43.09299 99.84 715.8528		Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01295	0.03	0.2151
Mould Compound Polymer Phenol Formaldehyde resin (generio) 9003-35-4 2.19121 4.0 36.4 Polymer Epichlorohydrin/Diethyleneglycol Epoxy resin (generic) 25928-94-3 8.21704 15.0 136.5 Filler Silica fused 60676-86-0 40.53741 74.0 673.4 Flame retardant Metal hydroxide subtotal 54.78028 100 910 Post-plating Pure metal Tin (Sn) 7440-31-5 1.50495 100.0 25		Copper alloy	Iron (Fe)	7439-89-6	0.04316	0.1	0.717
Mould Compound Polymer Phenol Formaldehyde resin (generic) 9003-35-4 2.19121 4.0 36.4 Polymer Epichlorohydrin/Diethyleneglycol Epoxy resin (generic) 25928-94-3 8.21704 15.0 136.5 Filler Silica fused 60676-86-0 40.53741 74.0 673.4 Flame retardant Metal hydroxide Subtotal 54.78028 100 910 Post-plating Pure metal Tin (Sn) 7440-31-5 1.50495 100.0 25		Copper alloy	Copper (Cu)	7440-50-8	43.09299	99.84	715.8528
Compound Polymer Phenol Formaldehyde resin (generic) 9003-35-4 2.19121 4.0 36.4 Polymer Epichlorohydrin/Diethyleneglycol Epoxy resin (generic) 25928-94-3 8.21704 15.0 136.5 Filler Silica fused 60676-86-0 40.53741 74.0 673.4 Flame retardant Metal hydroxide 3.83462 7.0 63.7 Post-plating Pure metal Tin (Sn) 7440-31-5 1.50495 100.0 25 Subtotal 1.50495 100 25				Subtotal	43.16205	100	717
Filler Silica fused 60676-86-0 40.53741 74.0 673.4 Flame retardant Metal hydroxide 3.83462 7.0 63.7 Post-plating Pure metal Tin (Sn) 7440-31-5 1.50495 100 25		Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.19121	4.0	36.4
Flame retardant Metal hydroxide 3.83462 7.0 63.7		Polymer		25928-94-3	8.21704	15.0	136.5
Retardant Metal hydroxide 3.83462 7.0 63.7 Subtotal 54.78028 100 910 Post-plating Pure metal Tin (Sn) 7440-31-5 1.50495 100.0 25 Subtotal 1.50495 100 25		Filler	Silica fused	60676-86-0	40.53741	74.0	673.4
Post-plating Pure metal Tin (Sn) 7440-31-5 1.50495 100.0 25 Subtotal 1.50495 100 25			Metal hydroxide		3.83462	7.0	63.7
Subtotal 1.50495 100 25				Subtotal	54.78028	100	910
	Post-plating	Pure metal	Tin (Sn)	7440-31-5	1.50495	100.0	25
Total 99.99999 100 1661.18148				Subtotal	1.50495	100	25
				Total	99.99999	100	1661.18148

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